IEEE P802.11  
Wireless LANs

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| TGbe March to May 2022 teleconference minutes | | | | |
| Date: 2022-04-05 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
| Dennis Sundman | Ericsson |  |  | dennis.sundman@ericsson.com |
|  |  |  |  |  |

Abstract

This document contains the minutes for March to May 2022 TGbe teleconferences.

Revision:

* Rev 0: Initial version of the document.

# 7th Conf. Call: Mar 16 (10:00–12:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>

# 8th Conf. Call: Mar 17 (19:00–21:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>

# 9th Conf. Call: Mar 21 (19:00–21:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>

# 10th Conf. Call: Mar 23 (10:00–12:00 ET)–JOINT

1. Call the meeting to order
2. IEEE 802 and 802.11 IPR policy and procedure
   1. Patent Policy: Ways to inform IEEE:
      * Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
      * Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
      * Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks up.**

* 1. Copyright Policy: Participants are advised that
     + IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
     + Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy
  2. **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures

1. Attendance reminder.
   1. Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
   2. Please record your attendance during the conference call by using the IMAT system:
      * 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.
   3. If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Dennis Sundman ([dennis.sundman@ericsson.com](mailto:dennis.sundman@ericsson.com)) and Alfred Asterjadhi
   4. Please ensure that the following information is listed correctly when joining the call:
      * "[voter status] First Name Last Name (Affiliation)"
      * Abouelseoud, Mohamed Apple Inc.
      * Aboulmagd, Osama Huawei Technologies Co., Ltd
      * Adhikari, Shubhodeep Broadcom Corporation
      * Ajami, Abdel Karim Qualcomm Incorporated
      * Ansley, Carol Cox Communications Inc.
      * Asterjadhi, Alfred Qualcomm Incorporated
      * Baek, SunHee LG ELECTRONICS
      * baron, stephane Canon Research Centre France
      * Bredewoud, Albert Broadcom Corporation
      * Cao, Rui NXP Semiconductors
      * Carney, William Sony Group Corporation
      * Chemrov, Kirill IITP RAS
      * Chitrakar, Rojan Panasonic Asia Pacific Pte Ltd.
      * Chng, Shi Baw BAWMAN LLC
      * Choi, Jinsoo LG ELECTRONICS
      * Chu, Liwen NXP Semiconductors
      * CHUN, JINYOUNG LG ELECTRONICS
      * Coffey, John Realtek Semiconductor Corp.
      * Dong, Xiandong Xiaomi Inc.
      * Duan, Ruchen SAMSUNG
      * Erkucuk, Serhat Ofinno
      * Fan, Shuang ZTE Corporation
      * Fang, Yonggang Mediatek
      * Fischer, Matthew Broadcom Corporation
      * Gu, Xiangxin Unisoc
      * Haasz, Jodi IEEE Standards Association (IEEE-SA)
      * Handte, Thomas Sony Corporation
      * Hart, Brian Cisco Systems, Inc.
      * Ho, Duncan Qualcomm Incorporated
      * Hsu, Ostrovsky Xiaomi Inc.
      * Hu, Chunyu Facebook
      * Huang, Lei Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * Huq, Kazi Mohammed Saidul Ofinno
      * Jang, Insun LG ELECTRONICS
      * Kakani, Naveen Qualcomm Incorporated
      * Kamel, Mahmoud InterDigital, Inc.
      * Kasher, Assaf Qualcomm Incorporated
      * kim, Jiin LG ELECTRONICS
      * Kim, Myeong-Jin SAMSUNG
      * Kim, Sang Gook LG ELECTRONICS
      * Kim, Sanghyun WILUS Inc
      * Kim, Yongho Korea National University of Transportation
      * Kim, Youhan Qualcomm Incorporated
      * Klein, Arik Huawei Technologies Co., Ltd
      * Ko, Geonjung WILUS Inc.
      * Lalam, Massinissa SAGEMCOM BROADBAND SAS
      * Lanante, Leonardo Ofinno
      * Lee, Wookbong SAMSUNG
      * Levesque, Chris Qorvo
      * Levitsky, Ilya IITP RAS
      * Li, Jialing Qualcomm Technologies, Inc.
      * Li, Yapu Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * Lim, Dong Guk LG ELECTRONICS
      * Loginov, Vyacheslav IITP RAS
      * Lorgeoux, Mikael Canon Research Centre France
      * Lou, Hanqing InterDigital, Inc.
      * Lu, kaiying MediaTek Inc.
      * Lu, Liuming Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * McCann, Stephen Huawei Technologies Co., Ltd
      * Montemurro, Michael Huawei Technologies Co., Ltd
      * Moon, Juseong Korea National University of Transportation
      * Naik, Gaurang Qualcomm Incorporated
      * Namboodiri, Vamadevan SAMSUNG ELECTRONICS
      * noh, yujin Senscomm
      * Ozbakis, Basak VESTEL
      * Palayur, Saju Maxlinear Inc
      * Pare, Thomas MediaTek Inc.
      * Park, Eunsung LG ELECTRONICS
      * Patil, Abhishek Qualcomm Incorporated
      * Patwardhan, Gaurav Hewlett Packard Enterprise
      * Petrick, Albert InterDigital, Inc.
      * Ratnam, Vishnu Samsung Research America
      * Rosdahl, Jon Qualcomm Technologies, Inc.
      * Ryu, Kiseon Ofinno
      * Schelstraete, Sigurd MaxLinear
      * Sevin, Julien Canon Research Centre France
      * Shafin, Rubayet Samsung Research America
      * Shilo, Shimi Huawei Technologies Co., Ltd
      * Shirakawa, Atsushi SHARP CORPORATION
      * Shu, Tongxin Huawei Technologies Co., Ltd
      * SUH, JUNG HOON Huawei Technologies Co., Ltd
      * Sun, Bo ZTE Corporation
      * Sun, Yanjun Qualcomm Incorporated
      * Taori, Rakesh Infineon Technologies
      * Tian, Bin Qualcomm Incorporated
      * Torab Jahromi, Payam Facebook
      * Tsodik, Genadiy Huawei Technologies Co., Ltd
      * Varshney, Prabodh Nokia
      * Verenzuela, Daniel Sony Corporation
      * Verma, Sindhu Broadcom Corporation
      * Vermani, Sameer Qualcomm Incorporated
      * VIGER, Pascal Canon Research Centre France
      * Wang, Qi Apple, Inc.
      * Wei, Dong NXP Semiconductors
      * Wentink, Menzo Qualcomm Incorporated
      * Wu, Kanke Qualcomm Incorporated
      * Wu, Tianyu Apple, Inc.
      * Wullert, John Peraton Labs
      * Xin, Yan Huawei Technologies Co., Ltd
      * Yang, Jay Nokia
      * Yang, Steve TS MediaTek Inc.
      * Yano, Kazuto Advanced Telecommunications Research Institute International (ATR)
      * Yi, Yongjiang Spreadtrum Communication USA Inc.
      * Yukawa, Mitsuyoshi Canon, Inc.
      * Zhang, Jiayi Ofinno
2. Announcements: None.
3. Agenda.
   1. Agenda approved with unanimous consent.
4. Status Update and Guidelines:[*396r3*](https://mentor.ieee.org/802.11/dcn/22/11-22-0396-03-00be-guidelines-update.pptx) *and* [*984r13*](https://mentor.ieee.org/802.11/dcn/20/11-20-0984-13-00be-tgbe-teleconference-guidelines.docx)
   1. Alfred goes through: [523r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0523-00-00be-guidelines-status-and-update.pptx)
      * No discussion.
   2. Alfred goes through: [984r13](https://mentor.ieee.org/802.11/dcn/20/11-20-0984-13-00be-tgbe-teleconference-guidelines.docx)
      * No discussion.
5. Technical Submissions**: CR**
   1. [202r5](https://mentor.ieee.org/802.11/dcn/22/11-22-0202-05-00be-cr-for-eht-ul-mu-operation.docx) CR-for-EHT-UL-MU-Operation Jason Y. Guo [11C SP-10’]

Jason goes through the CRs.

Some discussion.

SP: Do you agree to resolve the following CIDs listed in xxx and incorporate the text changes into the latest TGbe draft?

* 5780, 5851, 7792, 8054, 5112, 5491, 6803, 6806, 8135, 7065, 7066

Discussion: Some discussion.

Result: Y/N/A/No-answer: 32/38/41/45.

* 1. [2014r2](https://mentor.ieee.org/802.11/dcn/21/11-21-2014-02-00be-cr-for-35-5-3-part3.docx) cr-for-35.5.3\_part3 Jinyoung Chun [1C SP-5’]

Jinyoung goes through the CRs.

SP: Do you agree to resolve the following CIDs listed in [2014r2](https://mentor.ieee.org/802.11/dcn/21/11-21-2014-02-00be-cr-for-35-5-3-part3.docx) and incorporate the text changes into the latest TGbe draft?

* 8370

Result: Supported with no objection from the group.

* 1. [2012r2](https://mentor.ieee.org/802.11/dcn/21/11-21-2012-02-00be-cr-for-35-5-3-part1.docx) cr-for-35.5.3\_part1 Jinyoung Chun [1C SP-5’]

Jinyoung goes through the CRs.

SP: Do you agree to resolve the following CIDs listed in [2012r2](https://mentor.ieee.org/802.11/dcn/21/11-21-2012-02-00be-cr-for-35-5-3-part1.docx) and incorporate the text changes into the latest TGbe draft?

* 5564

Result: Supported with no objection from the group.

* 1. [452r2](https://mentor.ieee.org/802.11/dcn/22/11-22-0452-02-00be-cr-trigger-frame-and-ss.docx) CR Trigger frame and SS Yanjun Sun [10C 20’]

Yanjun goes through the CRs.

Some discussion.

SP: Do you agree to resolve the following CIDs listed in [452r2](https://mentor.ieee.org/802.11/dcn/22/11-22-0452-02-00be-cr-trigger-frame-and-ss.docx) and incorporate the text changes into the latest TGbe draft?

* 6937,4658,6077,5312,5313,4963,7330,4005,~~8067,6694~~

Discussion: No discussion at the SP itself.

Result: Supported with no objection from the group.

* 1. [349r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0349-01-00be-cr-discussion-of-nstr-and-emlsr.pptx) CR Discussion of NSTR and EMLSR Yunbo Li [1C 20’]

Yunbo goes through the CR. The comment recommends making EMLSR mandatory at AP side. The resolution is backed up with extensive simulations. The recommendation is reject.

Discussion:

* 1. SP: Do you agree to resolve the following CIDs listed in [349r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0349-01-00be-cr-discussion-of-nstr-and-emlsr.pptx) and incorporate the text changes into the latest TGbe draft?
* 5773

Discussion: Yes. Ran out of time.

1. AoB:
2. Adjourn

# 11th Conf. Call: Mar 24 (10:00–12:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>

# 12th Conf. Call: Mar 28 (10:00–12:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>

# 13th Conf. Call: Mar 30 (10:00–12:00 ET)–JOINT

1. The Chair Alfred Asterjadhi calls the meeting to order at 10:01 ET. Today’s agenda can be found in [428r11](https://mentor.ieee.org/802.11/dcn/22/11-22-0428-11-00be-mar-may-tgbe-teleconference-agenda.docx).
2. IEEE 802 and 802.11 IPR policy and procedure
   1. Patent Policy: Ways to inform IEEE:
      1. Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
      2. Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
      3. Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks up.**

* 1. Copyright Policy: Participants are advised that
     1. IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
     2. Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy
  2. **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures

1. Attendance reminder.
   1. Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
   2. Please record your attendance during the conference call by using the IMAT system:
      1. 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.
   3. If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Dennis Sundman ([dennis.sundman@ericsson.com](mailto:dennis.sundman@ericsson.com)) and Alfred Asterjadhi
   4. Please ensure that the following information is listed correctly when joining the call:
      1. "[voter status] First Name Last Name (Affiliation)"
      * Ajami, Abdel Karim Qualcomm Incorporated
      * Akhmetov, Dmitry Intel Corporation
      * Au, Kwok Shum Huawei Technologies Co., Ltd
      * B, Hari Ram NXP Semiconductors
      * Baek, SunHee LG ELECTRONICS
      * Bankov, Dmitry IITP RAS
      * Batra, Anuj Apple, Inc.
      * Carney, William Sony Group Corporation
      * CHERIAN, GEORGE Qualcomm Incorporated
      * Chitrakar, Rojan Panasonic Asia Pacific Pte Ltd.
      * Chng, Shi Baw BAWMAN LLC
      * Choi, Jinsoo LG ELECTRONICS
      * CHUN, JINYOUNG LG ELECTRONICS
      * Coffey, John Realtek Semiconductor Corp.
      * Dash, Debashis Apple, Inc.
      * Dong, Xiandong Xiaomi Inc.
      * Erkucuk, Serhat Ofinno
      * Fang, Yonggang Mediatek
      * feng, Shuling MediaTek Inc.
      * Fischer, Matthew Broadcom Corporation
      * Gu, Xiangxin Unisoc
      * GUIGNARD, Romain Canon Research Centre France
      * Haider, Muhammad Kumail Facebook
      * Handte, Thomas Sony Corporation
      * Hervieu, Lili Cable Television Laboratories Inc. (CableLabs)
      * Ho, Duncan Qualcomm Incorporated
      * Hsieh, Hung-Tao MediaTek Inc.
      * Hsu, Ostrovsky Xiaomi Inc.
      * Hu, Chunyu Facebook
      * Huang, Lei Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * Huang, Po-Kai Intel Corporation
      * Huq, Kazi Mohammed Saidul Ofinno
      * Ibrahim, Ahmed Samsung Research America
      * Jung, Insik LG ELECTRONICS
      * Khorov, Evgeny IITP RAS
      * kim, Jiin LG ELECTRONICS
      * Kim, Sang Gook LG ELECTRONICS
      * Kim, Sanghyun WILUS Inc
      * Kim, Yongho Korea National University of Transportation
      * Kim, Youhan Qualcomm Incorporated
      * Kipness, Michael IEEE Standards Association (IEEE-SA)
      * Klein, Arik Huawei Technologies Co., Ltd
      * Ko, Geonjung WILUS Inc.
      * Koundourakis, Michail Samsung Cambridge Solution Centre
      * Lalam, Massinissa SAGEMCOM BROADBAND SAS
      * Lanante, Leonardo Ofinno
      * Lee, Wookbong SAMSUNG
      * Levesque, Chris Qorvo
      * Levy, Joseph InterDigital, Inc.
      * Li, Yapu Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * Lim, Dong Guk LG ELECTRONICS
      * Loginov, Vyacheslav IITP RAS
      * Lu, Liuming Guangdong OPPO Mobile Telecommunications Corp.,Ltd
      * Lumbatis, Kurt CommScope, Inc.
      * Lyakh, Mikhail ON Semiconductor
      * Ma, Li MediaTek Inc.
      * Max, Sebastian Ericsson AB
      * McCann, Stephen Huawei Technologies Co., Ltd
      * Monajemi, Pooya Cisco Systems, Inc.
      * Montreuil, Leo Broadcom Corporation
      * Moon, Juseong Korea National University of Transportation
      * Namboodiri, Vamadevan SAMSUNG ELECTRONICS
      * Nezou, Patrice Canon Research Centre France
      * Ng, Boon Loong Samsung Research America
      * noh, yujin Senscomm
      * Ozbakis, Basak VESTEL
      * Palayur, Saju Maxlinear Inc
      * Park, Eunsung LG ELECTRONICS
      * Patil, Abhishek Qualcomm Incorporated
      * Patwardhan, Gaurav Hewlett Packard Enterprise
      * Petrick, Albert InterDigital, Inc.
      * Ratnam, Vishnu Samsung Research America
      * Rosdahl, Jon Qualcomm Technologies, Inc.
      * Ryu, Kiseon Ofinno
      * Sato, Takuhiro SHARP CORPORATION
      * Schelstraete, Sigurd MaxLinear
      * Sevin, Julien Canon Research Centre France
      * Shafin, Rubayet Samsung Research America
      * Shilo, Shimi Huawei Technologies Co., Ltd
      * Srivatsa, Veena Synaptics
      * SUH, JUNG HOON Huawei Technologies Co., Ltd
      * Taori, Rakesh Infineon Technologies
      * Thakur, Sidharth Apple, Inc.
      * Tian, Bin Qualcomm Incorporated
      * Torab Jahromi, Payam Facebook
      * Varshney, Prabodh Nokia
      * Verenzuela, Daniel Sony Corporation
      * Verma, Sindhu Broadcom Corporation
      * Vermani, Sameer Qualcomm Incorporated
      * Wang, Chao Chun MediaTek Inc.
      * Wang, Qi Apple, Inc.
      * Wei, Dong NXP Semiconductors
      * Wentink, Menzo Qualcomm Incorporated
      * Wilhelmsson, Leif Ericsson AB
      * Wu, Kanke Qualcomm Incorporated
      * Wu, Tianyu Apple, Inc.
      * Yan, Aiguo Zeku
      * Yang, Jay Nokia
      * Yang, Steve TS MediaTek Inc.
      * Yano, Kazuto Advanced Telecommunications Research Institute International (ATR)
      * Yee, James MediaTek Inc.
      * Yi, Yongjiang Spreadtrum Communication USA Inc.
      * Yong, Su Khiong Apple, Inc.
      * Zhang, Jiayi Ofinno
      * Zhou, Pei Guangdong OPPO Mobile Telecommunications Corp.,Ltd
2. Announcements: None.
3. Agenda.
   1. For the first document, could you replace the document 452r3 with 537r1?
   2. In the last call I ran a SP for 202r6, I want to run it again based on offline discussion.
   3. Agenda approved with unanimous consent.
4. TGbe Queues Status [10’]
   1. Resolution pace
   2. Overview of docs in quarantine
      1. Review docs’ status and check for any progress on any CID.
   3. Provide DCNs and ETAs for unresolved CIDs: Deadline: April 5th, 2022.
      1. Afterwards, CIDs assigned to unresponsive assignees to be reassigned
5. Agenda amended to include Quarantined documents approved with unanimous consent.
6. Technical Submissions**: CR**
   1. [537r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0537-01-00be-cr-trigger-subclause-structure-8067-6694.docx) Yanjun Sun [2C SP-5’]

Yanjun goes through the updates based on offline discussions.

SP1: Do you agree to resolve the following CIDs listed in [537r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0537-01-00be-cr-trigger-subclause-structure-8067-6694.docx) and incorporate the text changes into the latest TGBe draft?

* 8067, 6694.

Discussion: None

Result: Supported with no objection from the group.

* 1. [356r3](https://mentor.ieee.org/802.11/dcn/22/11-22-0356-03-00be-cr-for-power-save-of-nstr-mobile-ap-mld.docx) CR 4 power save of NSTR mobile AP MLD Guogang Huang [2C 15’]

Guogang goes through the CRs.

SP2: To be run next week.

* 1. [388r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0388-00-00be-cc36-cr-on-cid-5497.doc) CC36 CR on CID 5497 Ross Jian Yu [1C 5’]

Ross shows the resolution.

SP3: Do you agree to resolve the following CIDs listed in [388r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0388-00-00be-cc36-cr-on-cid-5497.doc) and incorporate the text changes into the latest TGBe draft?

* 5497

Discussion:

C: What is the result?

A: Revised.

Result: Supported with no objection from the group.

* 1. [209r0](https://mentor.ieee.org/802.11/dcn/21/11-21-0209-00-00be-mlo-broadcast-architecture.pptx) MLO Broadcast Architecture Mike Montemurro [1C? 25’]

Mike goes through the document explaining how multiple APs, and MLD AP connects to the wired gateway through different aspects.

Discussion: Some discussion regarding how the different set-ups work.

SP deferred for the next week.

* 1. [525r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0525-00-00be-cc36-cr-on-cid-4300-and-5947.docx) CR on CID 4300 And 5947 Yanjun Sun [2C 10’]

Yanjun goes through the CIDs.

SP5: Do you agree to resolve the following CIDs listed in [525r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0525-00-00be-cc36-cr-on-cid-4300-and-5947.docx) and incorporate the text changes into the latest TGBe draft?

* 2065, 4285.
  1. [548r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0548-00-00be-cc36-comment-resolution-subclause-35-15.docx) Comment resolution subclause 35.15 Liwen Chu [2C 20’]

Discussion:

C: EHT-MCS that are supported by all EHT STAs. The APs need to know all capabilities of the associated STAs?

C: I don’t think we need to include the IBSS and MBSS.

C: If we remove those, do we still maintain backwards compatibility with the PAR?

1. AoB: No time.
2. Adjourned at 12:00.

# 14th Conf. Call: Mar 31 (10:00–12:00 ET)–MAC

MAC ad-hoc:

* <https://mentor.ieee.org/802.11/dcn/22/11-22-0516-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2022.docx>